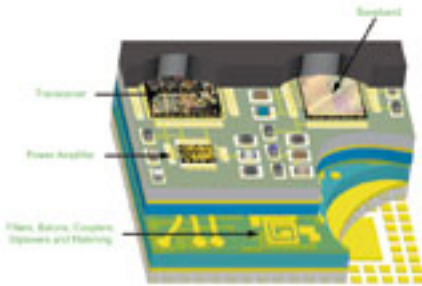


Integrated Substrate Packages for Wireless Applications



Jacket Micro Devices, Inc. (JMD) announces highly integrated substrate packages for wireless applications. The proprietary multi-layer organic (MLO) technology is suitable for front-end modules (FEMs) and emerging embedded applications, combining baseband, transceiver and an RF front-end in a single package. A proprietary MLO SiP technology provides a cost-effective high performance alternative to ceramic packages. High volume SiP substrates and design services are offered that use an extensive RF component library.

www.jacketmicro.com
404-961-7240

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